

AMENDMENTS TO THE CLAIMS

Claims 1-20 (cancelled)

Claim 21. (currently amended) An integrated structure including a semiconductor device and connector structures for connecting the semiconductor device to a motherboard, the integrated structure comprising:

a first layer having a first set of conductors disposed therein, the first layer having an upper surface and a lower surface, the first set of conductors connecting to bonding pads disposed on the lower surface, the bonding pads being spaced with respect to each other with a first spacing distance in accordance with a required spacing of connections to the motherboard;

the semiconductor device;

a second layer disposed on the semiconductor device and in contact therewith, the second layer having a second set of conductors disposed therein connecting to the semiconductor device, the second layer facing the first layer;

a plurality of connectors connecting the first set of conductors to the second set of conductors, said connectors being one of (1) a set of stud/via connectors and (2) a set of C4 connectors, said connectors being spaced with respect to each other with a second spacing distance less than the first spacing distance;

a support structure attached to the upper surface of the first layer and in contact therewith and surrounding the semiconductor device, a gap between said support structure and the semiconductor device being filled with a fill material; and

connector structures connected to the bonding pads.

Claim 22. An integrated structure according to claim 21, wherein the connector structures form one of a pin grid array (PGA), a ball grid array (BGA), a C4 array and a land grid array (LGA).

Claim 23. (original) An integrated structure according to claim 21, wherein the motherboard is characterized by a thermal coefficient of expansion (TCE), and the support structure is provided with a TCE approximately that of the motherboard.

Claim 24. (original) An integrated structure according to claim 21, wherein the support structure has an area corresponding to an area occupied by the bonding pads.

Claim 25. (original) An integrated structure according to claim 21, wherein said plurality of connectors are a set of C4 connectors, and the fill material fills a gap between the semiconductor device and the first layer surrounding said C4 connectors.

Claim 26. (original) An integrated structure according to claim 21, wherein said plurality of connectors are a set of stud/via connectors, and said integrated structure further comprises a third layer interposed between the first layer and the second layer and having vias formed therein.